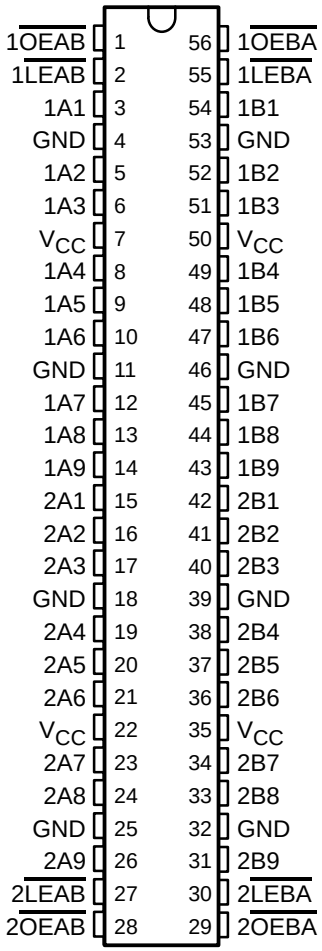
- **Members of the Texas Instruments *Widebus*™ Family**
- **3-State True Outputs**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Pin Spacings**

54AC16472 . . . WD PACKAGE
74AC16472 . . . DL PACKAGE
(TOP VIEW)



description

The ’AC16472 are 18-bit registered transceivers that contain two sets of D-type latches for temporary storage of data flowing in either direction. They can be used as two 9-bit transceivers or one 18-bit transceiver. Separate latch-enable ($\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}$) and output-enable ($\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$) inputs are provided for each register to permit independent control in either direction of data flow.

When $\overline{\text{OEAB}}$ and $\overline{\text{LEAB}}$ are both low, the A-to-B latches are transparent; a subsequent low-to-high transition of $\overline{\text{LEAB}}$ puts the A latches in the storage mode. With $\overline{\text{OEAB}}$ low, the B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires the use of the $\overline{\text{LEBA}}$ and $\overline{\text{OEBA}}$ inputs.

The 74AC16472 is packaged in TI’s shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16472 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16472 is characterized for operation from –40°C to 85°C.

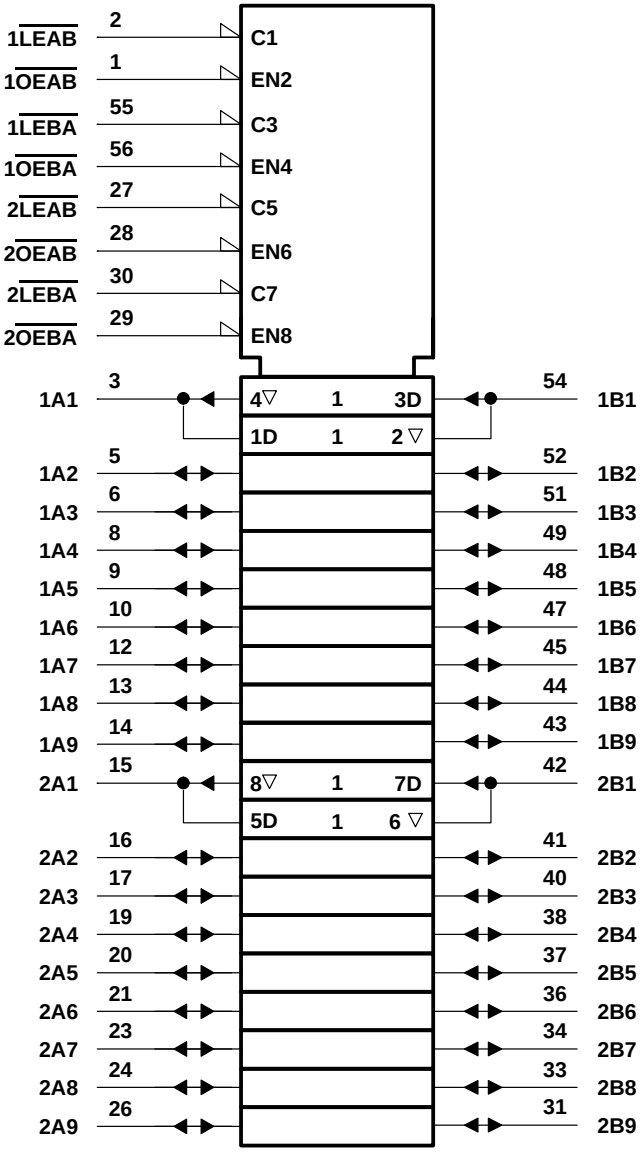
FUNCTION TABLE†

INPUTS			OUTPUT
$\overline{\text{LEAB}}$	OEAB	A	B
X	H	X	Z
H	L	X	B_0‡
L	L	H	H
L	L	L	L

† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{\text{LEBA}}$ and $\overline{\text{OEBA}}$.

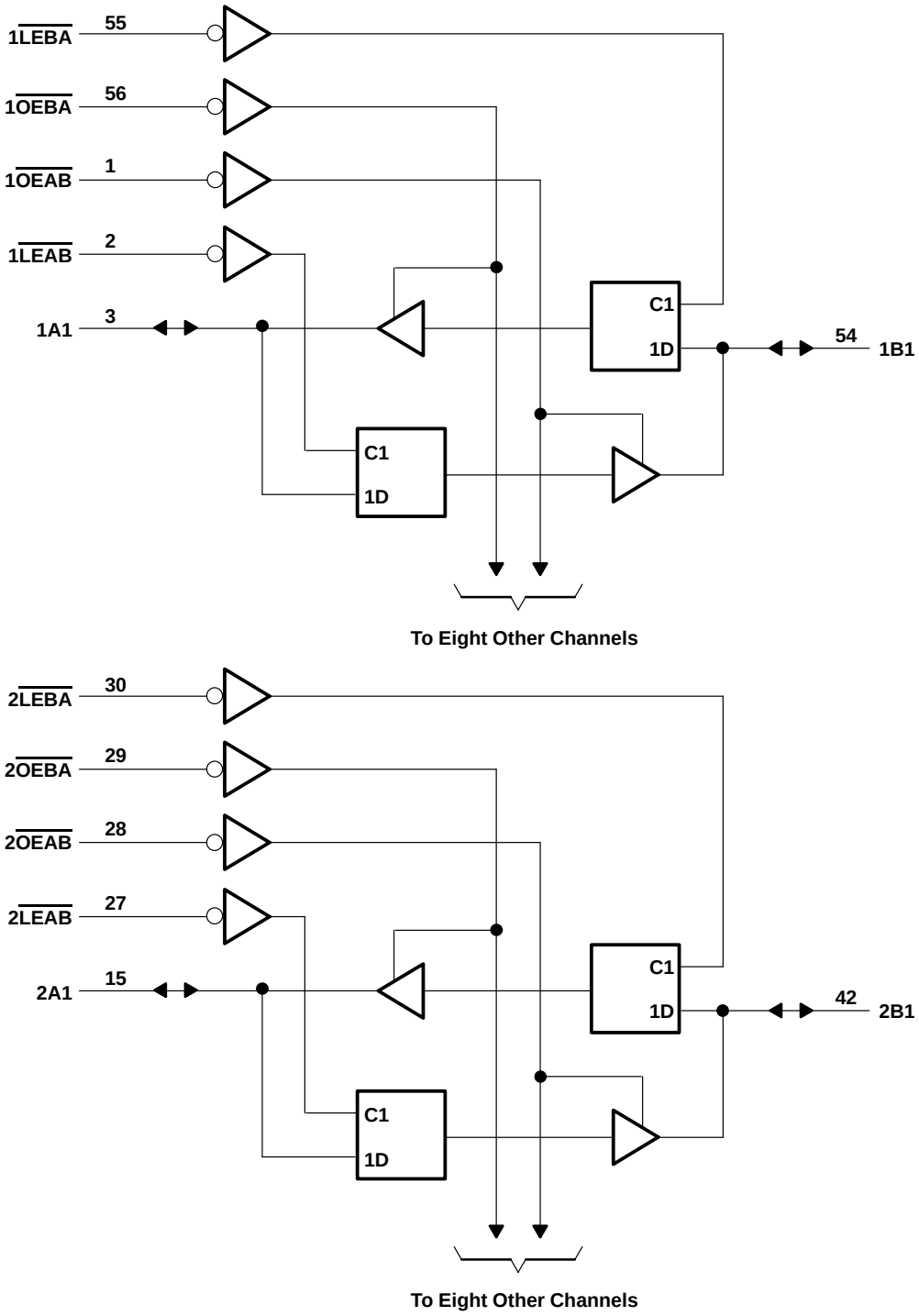
‡ Output level before the indicated steady-state input conditions were established

logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) . . . . . ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±50 mA
Continuous current through V_{CC} or GND . . . . . ±450 mA
Maximum power package dissipation at T_A = 55°C (in still air) (see Note 2): DL package . . . . . 1.4 W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

			54AC16472			74AC16472			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		3	5	5.5	3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			2.1			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 5.5 V	3.85			3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9			0.9	V
		V_{CC} = 4.5 V			1.35			1.35	
		V_{CC} = 5.5 V			1.65			1.65	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			–4			–4	mA
		V_{CC} = 4.5 V			–24			–24	
		V_{CC} = 5.5 V			–24			–24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12			12	mA
		V_{CC} = 4.5 V			24			24	
		V_{CC} = 5.5 V			24			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	0		10	ns/V
T_A	Operating free-air temperature		–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			54AC16472		74AC16472		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = –50 µA	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		I_{OH} = –4 mA	3 V	2.58			2.48		2.48		
		I_{OL} = –24 mA	4.5 V	3.94			3.8		3.8		
			5.5 V	4.94			4.8		4.8		
		I_{OH} = –75 mA†	5.5 V				3.85		3.85		
V_{OL}		I_{OL} = 50 µA	3 V			0.1		0.1		0.1	V
			4.5 V			0.1		0.1		0.1	
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.44		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
			5.5 V			0.36		0.44		0.44	
		I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80		80	µA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		3						pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		11.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		54AC16472		74AC16472		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low	4		4		4		ns
t_{su}	Setup time, data before $\overline{LEAB}$ or $\overline{LEBA}$ ↑	0.5		0.5		0.5		ns
t_h	Hold time, data after $\overline{LEAB}$ or $\overline{LEBA}$ ↑	3.5		3.5		3.5		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T_A = 25°C		54AC16472		74AC16472		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low	4		4		4		ns
t_{su}	Setup time, data before $\overline{LEAB}$ or $\overline{LEBA}$ ↑	0.5		0.5		0.5		ns
t_h	Hold time, data after $\overline{LEAB}$ or $\overline{LEBA}$ ↑	2.5		2.5		2.5		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16472		74AC16472		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	3.5	8	12.5	3.5	14.2	3.5	14.2	ns
t_{PHL}			3.9	8.4	12.8	3.9	13.9	3.9	13.9	
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	4.8	10.3	15.6	4.8	17.9	4.8	17.9	ns
t_{PHL}			4.7	9.7	14.7	4.7	16.3	4.7	16.3	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	3.9	8.9	14	3.9	15.9	3.9	15.9	ns
t_{PZL}			5	11.2	17.6	5	19.7	5	19.7	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	4.4	7	9.4	4.4	10	4.4	10	ns
t_{PLZ}			4	6.4	8.7	4	9.4	4	9.4	

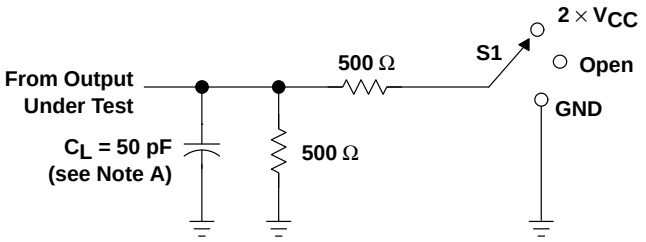
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16472		74AC16472		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	2.9	5.6	8.4	2.9	9.5	2.9	9.5	ns
t_{PHL}			3.1	6	8.7	3.1	9.6	3.1	9.6	
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	3.9	7.3	10.3	3.9	11.7	3.9	11.7	ns
t_{PHL}			3.7	6.9	9.7	3.7	10.9	3.7	10.9	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	3.1	6.2	8.9	3.1	10.2	3.1	10.2	ns
t_{PZL}			3.9	7.3	10.4	3.9	11.6	3.9	11.6	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	4.3	6.2	8.1	4.3	8.6	4.3	8.6	ns
t_{PLZ}			3.8	5.7	7.4	3.8	8	3.8	8	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

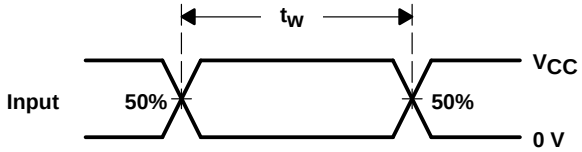
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C_L = 50 pF, f = 1 MHz	59	pF
		Outputs disabled		6	

PARAMETER MEASUREMENT INFORMATION

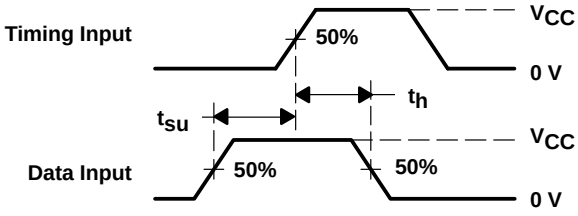


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT



VOLTAGE WAVEFORMS



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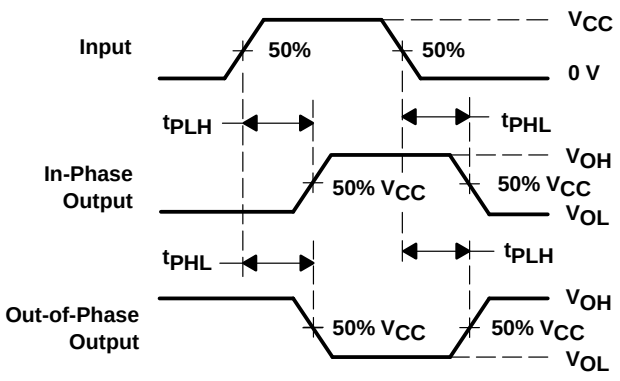
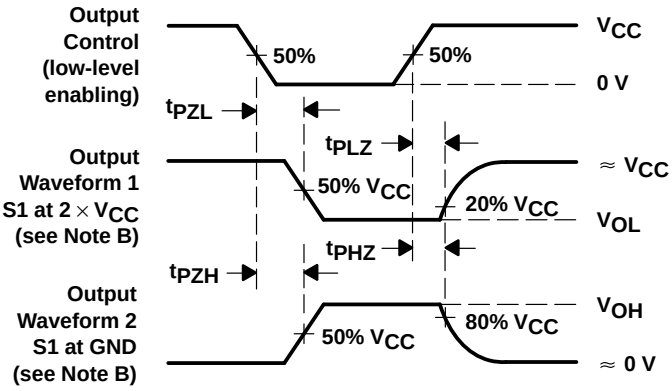


VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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